CLAIMS

[Claim 1]

An electronic component-mounting substrate comprising:

a substrate;

an electronic component mounted on at least one surface of the substrate; and

a peeling or falling prevention layer that coats the substrate and the electronic component, wherein

the peeling or falling prevention layer satisfies both the following (1) and (2):

(1) a rate of change X of a coefficient of static friction obtained in the following [Formula 1] is -50% or greater and 200% or smaller, where

$$X = (\mu k_{300} - \mu k_{100})/\mu k_{100} \times 100 \quad \text{[Formula 1]}$$

wherein μk_{100} is a coefficient of static friction at a 100-th reciprocating wear test of the peeling or falling prevention layer and μk_{300} is a coefficient of static friction at a 300-th reciprocating wear test of the peeling or falling prevention layer;

(2) an index Y obtained in the following [Formula 2] is 0.8 or greater and 20.0 or smaller where

$$Y = R_2/(R_1+A_1) \quad \text{[Formula 2]}$$

wherein R_1 is a radius of curvature of a curved surface of a corner part of the electronic component in a cross section of the electronic component-mounting substrate, R_2 is a radius of curvature of a corner part of the peeling or falling prevention layer in the cross section of the electronic component-mounting substrate and A_1 is a thickness of the corner part of the peeling or falling prevention layer in the cross section of the electronic component-mounting substrate.

[Claim 2]

The electronic component-mounting substrate according to claim 1, wherein

the peeling or falling prevention layer includes a binder (A) and a filler (B), and

a product of a BET specific surface area [m^2/g] of the filler (B)

and a content rate [mass%] of the filler (B) in 100 mass% of the peeling or falling prevention layer is 0.01 to 15 [mass%·m^2/g].

[Claim 3]

The electronic component-mounting substrate according to claim 1 or 2, wherein a thickness A_2 of the peeling or falling prevention layer is 5 to 300 μm.

[Claim 4]

An electronic device on which the electronic component-mounting substrate according to any one of claims 1 to 3 is mounted.